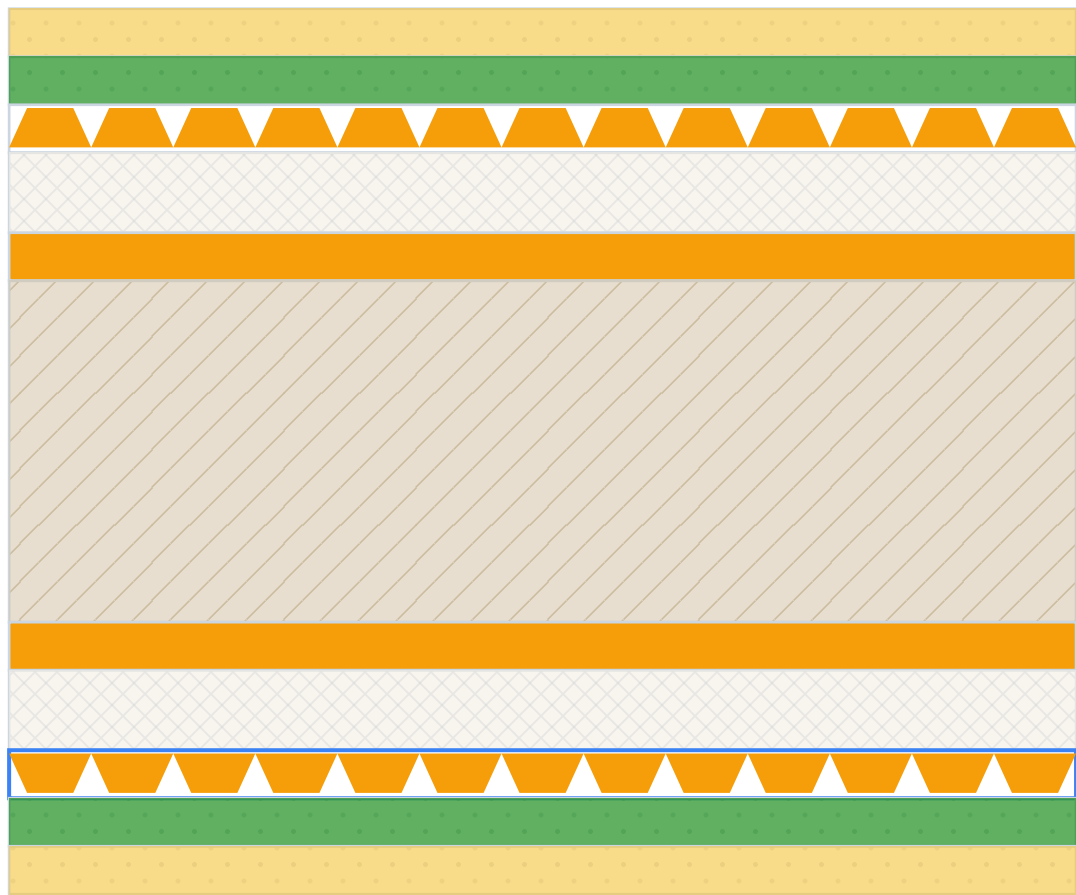


Top Surface Finish
 Top Solder Mask
L1
 Prepreg
L2
 Core
L3
 Prepreg
L4
 Bottom Solder Mask
 Bottom Surface Finish



4L-1.2-7628-2-1-30

Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.0525	0.0525		
FR4 · 7628	Prepreg	0.196	0.1715	43%	4.7
	Plane	0.035	0.035		
FR4	Core	0.63	0.63		4.6
	Plane	0.035	0.035		
FR4 · 7628	Prepreg	0.196	0.1715	43%	4.7
	Signal	0.0525	0.0525		
		0.020			
ENIG		0.005			

Thickness After Lamination: 1.148 mm
 Finished PCB Thickness: 1.198 mm ±10%
 Inner layer Residual copper ratio: 30%